

**IN THE SPECIFICATION:**

Amend the specification as follows:

Please replace the paragraph beginning at page 6, line 29 with the following rewritten paragraph:

In the construction of the semiconductor device 5 of the present embodiment, the electrical signal appearing on the electrode pad 8a of the chip 2 is forwarded to the electrode pad 8b on the circuit substrate 6 by way of a bonding wire 4 and further to an electrode pad 8c on the circuit substrate 6 by way of a conductor pattern 9 provided on the circuit substrate 6. The electrode pad 8c carries thereon a spherical or semi-spherical solder bump 7 or a suitable spherical electrode. It should be noted that the conductor pattern 9 on the circuit substrate 6 is covered by a solder resist layer 3b, and the solder bump 7 projects outwardly from the solder resist layer 3b that covers the surface of the circuit substrate 6 through a hole 7a in the solder resist layer 3b. It should be noted that the layer 3b is not illustrated in FIG. 3.